

Title (en)

MEASUREMENT OF COMPONENTS THAT HAVE BEEN MICRO-GALVANICALLY PRODUCED, USING A SAMPLE COMPONENT BY MEANS OF PHOTORESIST WEBS

Title (de)

VERMESSEN VON MIKROGALVANISCH HERGESTELLTEN BAUTEILEN DURCH SCHNITTBAUTEILE ÜBER LACKSTEGE

Title (fr)

MESURE DE PIECES FABRIQUEES PAR MICROGALVANISATION, AU MOYEN DE PIECES D'INTERSECTION SUR ARETES DE VERNIS

Publication

EP 1381824 A1 20040121 (DE)

Application

EP 02729860 A 20020409

Priority

- DE 0201289 W 20020409
- DE 10118274 A 20010412

Abstract (en)

[origin: DE10118274A1] Process for measuring micro-galvanically produced components having a three-dimensional deep-lithographically produced structure comprises forming a single or multiple layer component (23') by galvanic metal deposition; inserting a photoresist region (45); removing the photoresist region from the component; and measuring the opening structure in the region of previous lacquered edge (46) of the photoresist region using a measuring device. Preferred Features: The measuring device is a scanning electron microscope, a profile projector, a CCD or IR camera, or a microscope.

IPC 1-7

G01B 11/00; **C25D 1/00**; **G03F 7/00**; **F02M 61/00**; **B05B 1/00**

IPC 8 full level

G01B 11/00 (2006.01); **B05B 1/00** (2006.01); **C25D 1/00** (2006.01); **C25D 21/12** (2006.01); **F02M 51/06** (2006.01); **F02M 61/00** (2006.01); **F02M 61/16** (2006.01); **F02M 61/18** (2006.01); **F02M 65/00** (2006.01); **G01B 11/06** (2006.01); **G01B 11/26** (2006.01); **G03F 7/00** (2006.01)

CPC (source: EP US)

C25D 21/12 (2013.01 - EP US); **F02M 51/0671** (2013.01 - EP US); **F02M 61/166** (2013.01 - EP US); **F02M 61/168** (2013.01 - EP US); **F02M 61/1853** (2013.01 - EP US); **F02M 65/00** (2013.01 - EP US); **F02M 2200/9038** (2013.01 - EP US); **F02M 2200/9046** (2013.01 - EP US)

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